nexperia

## Quarterly Reliability Monitoring Results

Quarters: Q3/2021 to Q4/2022
Based on structural similarity

| Supplier <br> Nexperia B.V. |  | User Part Number PESD5Z3.3-Q |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Name of Laboratory |  | Part Description Nexperia DHAM SMD package | Protection |  |  |  |
| Based on AEC-Q101 Test |  | Test Conditions | Duration | \# Lots | \# Quantity | \# Rejects |
| \# E1 | TEST <br> Pre- and Post-Stress <br> Electrical Test | Tamb $=25^{\circ} \mathrm{C}$ | N/A | see below | all parts | see below |
| \# A1 | PC <br> Preconditioning | $\begin{aligned} & \text { JESD22-A113 } \\ & \text { Bake Tamb }=125^{\circ} \mathrm{C} \\ & \text { Soak Tamb }=85^{\circ} \mathrm{C}, \mathrm{RH}=85 \% \\ & \text { Reflow soldering } \end{aligned}$ | 24 hours 168 hours 3 cycles | 438 | 24630 | 0 |
| \# B1 | HTRB <br> High Temperature Reverse Bias | MIL-STD-750-1 <br> M1038 Method A <br> $\mathrm{Tj}=\mathrm{Tjmax}, \mathrm{Vr}=100 \%$ of max. datasheet reverse voltage | 1000 hours | 166 | 10040 | 0 |
| \# A4 | TC <br> Temperature Cycling | JESD22-A104 <br> $-65^{\circ} \mathrm{C}$ to Tjmax, not to exceed $150^{\circ} \mathrm{C}$ | 1000 cycles | 131 | 7760 | 0 |
| \# A3 or | UHAST <br> Unbiased HAST | $\begin{aligned} & \text { JESD22-A118 } \\ & \text { Tamb }=130^{\circ} \mathrm{C}, \mathrm{RH}=85 \% \end{aligned}$ | 96 hours | 131 | 7760 | 0 |
| \# A3 alt | AC <br> Autoclave | $\begin{aligned} & \text { JESD22-A102 } \\ & \text { Tamb }=121^{\circ} \mathrm{C}, \mathrm{RH}=100 \% \\ & \text { Pressure }=205 \mathrm{kPa}(29.7 \text { psia) } \end{aligned}$ |  |  |  |  |
| \# A2 alt | H3TRB <br> High Humidity High Temperature Reverse Bias | JESD22-A101 <br> Tamb $=85^{\circ} \mathrm{C}, \mathrm{RH}=85 \%, \mathrm{VR}=80 \%$ of rated reverse voltage ${ }^{[1]}$ | 1000 hours | 131 | 7760 | 0 |
| \# A5 | IOL <br> Intermittent Operating Life | MIL-STD-750 Method 1037 <br> ton = toff, devices powered to insure $\Delta T j=$ $100^{\circ} \mathrm{C}$ for 15000 cycles | 1000 hours | n.a. | n.a. | n.a. |
| \# C8 | RSH <br> Resistance to Solder Heat | $\begin{aligned} & \text { JESD22-A111 } \\ & 260^{\circ} \mathrm{C} \pm 5^{\circ} \mathrm{C} \end{aligned}$ | 10 s | 45 | 1350 | 0 |
| \# C10 | SD <br> Solderability | J-STD-002 |  | 111 | 1110 | 0 |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test \#B1)
Confidence level $60 \%$, derated to $55^{\circ} \mathrm{C}$, activation energy 0.7 eV , test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) |
| :--- | :--- | :--- | :--- | :--- |
| Nexperia  10040  <br> DHAM Protection  0 | 0,42 |  |  |  |

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